

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph on page 8 lines 2-11, with the following amended paragraph:

In the exemplary embodiment shown in top view 200 and side view 201 in Figures 2A and 2B, respectively, a microstrip with a round wire bond 202 is closely spaced above a ribbon bond 203, on chip or package substrate 207. The round wire 202 and ribbon wire 203 would typically be dispensed together and tacked at either periodic intervals or continuously with, for example, ultraviolet (UV) cured epoxy 204 to maintain the proper spacing. This would require some modification of the bond pad geometry as shown in Figures 2A and 2B, where an additional bond pad 205 in close proximity provides a return path for the higher frequency components of the signal present on bond pad 206, compared to the conventional technique shown in Figures 1A and 1B where the return path is not clearly assigned.